

1	TEMP	
2		
3	GND	
4	VDD	
5	BAT	
6	STDBY	
7	CHRG	
8	CE	

VDD/CHRG/STDBY Pin Voltage	$V_{VDD/CHRG/STDBY}$	-0.3~36	V
VCE Pin Voltage	V_{CE}	-0.3~32	
BAT Pin Voltage	V_{BAT}	-5~15	
PROG Pin Voltage	V_{PROG}	-0.3~6	
TEMP Pin Voltage	V_{TEMP}	-0.3~15	
Operating Ambient Temperature Range	T_{OP}	-40~+85	°C
Storage Temperature	T_{stg}	-55~+150	°C
Lead Temperature (Soldering, 10s)	T_{solder}	260	°C
ESD	HBM	2000	V
	MM	200	V

CHRG Pin Output Current	I _{CHRG}	V _{DD} =5V;V _{CHRG} =1V	1	2.5	5	mA



BRCL4058NZZ

/

BRCL4058NZZ

USB

AC

1A

,

36V

6.8V



VDD

UVLO

PROG

1%

BAT

2.8V,

1/10

BAT

2.8V

BAT

BRCL4058NZZ

1/10



$I_{CH}=1000/R_{PROG}$

I_{CH}

R_{PROG}

R_{PROG}

200mA

$R_{PROG}=1000/0.2=5K$

R_{PROG}

1%

R_{PROG}

$R_{PROG}(K\Omega)$	$I_{CH}(mA)$
1	1000
1.2	830
1.5	666
5	200



BRCL4058NZZ

2ms

$T_{RECHARGE}$

BAT

4.05V

80

90



140

BRCL4058NZZ



UVLO

VDDVDD

VDD200mV



BRCL4058NZZ

VDD

VDD



BRCL4058NZZ

CHRGSTDBY

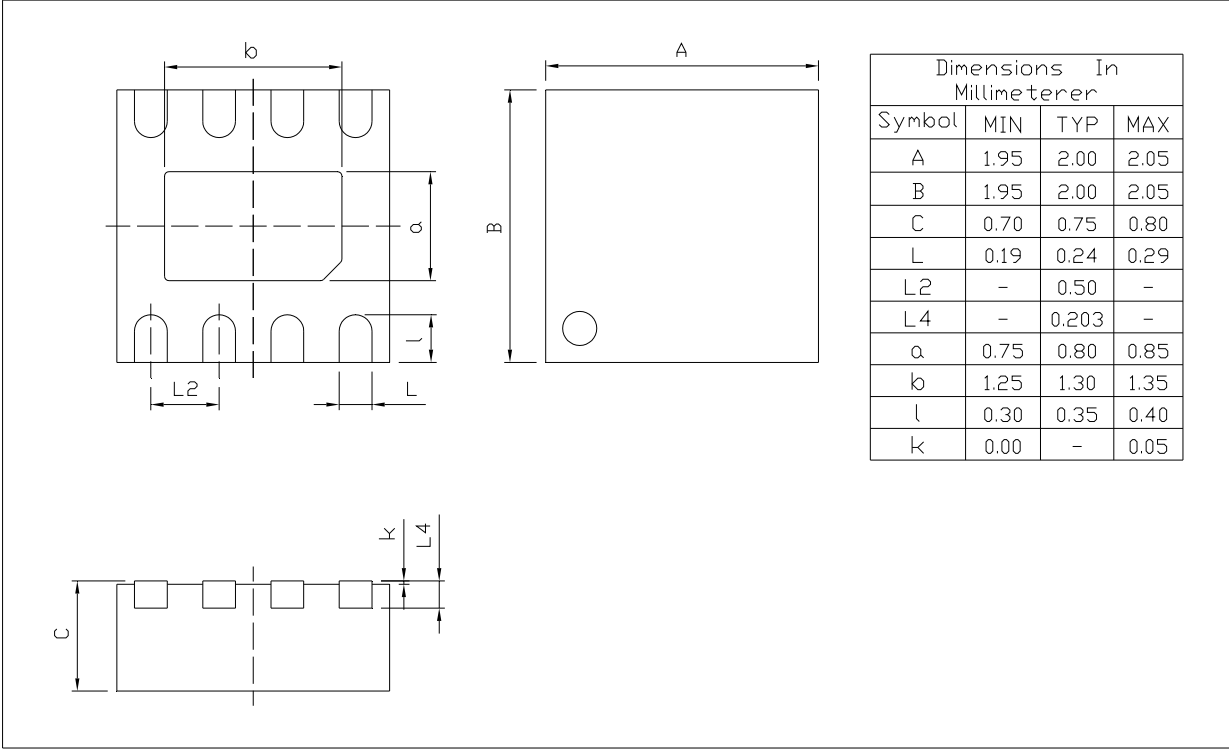
CHRGSTDBY

CHRGSTDBY

	CHRG/	STDBY/

DFN2 x2-8L-0.75

Unit:mm

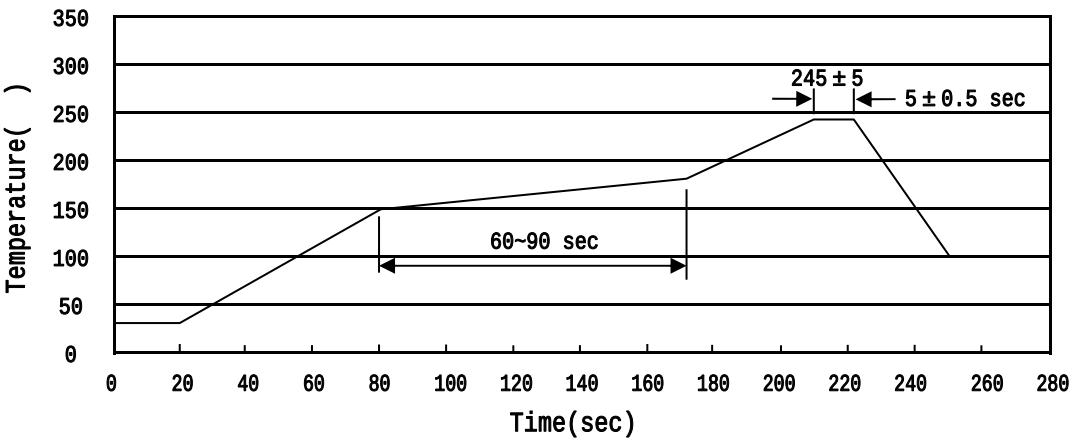


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Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;

1.Preheating:150~180 , Time:60~90sec.
- 2

245 5

5 0.5sec;

2.Peak Temp.:245 5 , Duration:5 0.5sec.
- 3

2 10 /sec.

3. Cooling Speed: 2~10 /sec.

260 5

10 1 sec.

Temp.:260±5

Time:10±1 sec

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
DFN2×2-8L	4,000	10	40,000	4	160,000	7 ×8	210×205×205	445×435×230

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